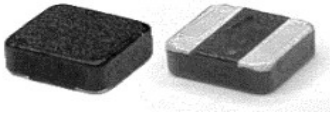


Molding Power Inductors -MTP Series



MTP Series



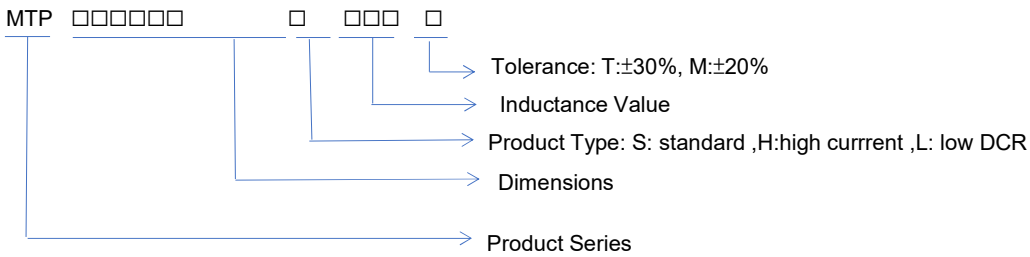
Description:

- High performance (Isat) realized by metal dust core.
- Low profile : 2.5mm x 2.0mm x 1.2mm
- Low loss realized with low DCR
- 100% lead (Pb) free meet RoHS standard
- Magnetically shielded, low EMI

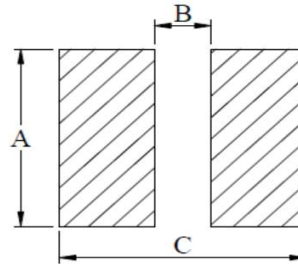
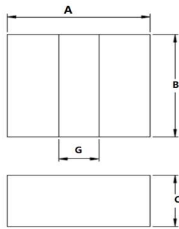
Applications:

- .DC/DC converter for CPU in Notebook PC
- .Cellular phones, LCD displays, HDDs, DVCs, DSCs, PDAs etc..
- .Thin type on-board power supply module for exchanger
- .VRM for server

Product Identification



Dimensions-mm



Dimensions-mm

TYPE	A	B	C	G
252012	2.5±0.2	2.0±0.2	1.2Max	1.0Typ.

Dimensions-mm

TYPE	A	B	C
252012	2.2	1.0	2.7

- No Marking

Molding Power Inductors -MTP Series

Electrical Characteristics

Part No.	Inductance (uH)	Tolerance (±%)	Test Freq.	Irms(A) Max.(Typ)	Isat(A) Max.(Typ)	RDC(mD) Max.(Typ)
MTP252012H1R0M	1.0	20	1MHz,1V	4.2(4.7)	3.0(3.3)	28(25)
MTP252012H1R5M	1.5	20	1MHz,1V	3.3(3.8)	2.7(2.7)	50(45)

Notes:

- All test data is referenced to 25°C ambient.
- Operating temperature range -55°C to +125°C (Including self - temperature rise)
- Irms(A):DC current(A) that will cause an approximate ΔT of 40°C (reference ambient temperature is 25°C)
- Isat(A):DC current(A) that will cause L0 to drop approximately 30%.
- Measure Equipment :
L : Wayne kerr 3260B/G LCR Meter (or equivalent), 1MHz 1V
RDC : CHEN HWA502BC/HP4338B (or equivalent)
Isat : Wayne kerr 3265B Bias Current Source (or equivalent)
Irms : Agilent 6641 SYSTEM DC POWER SUPPLY (or equivalent)
- Test Condition:
Temperature:26±3°C
Humidity:<70% RH
Frequency:1MHz 1V

Molding Power Inductors -MTP Series

Curve:

